

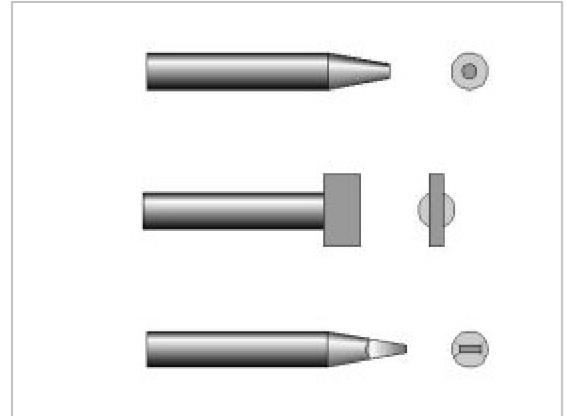
Bonding Tips

Instruction: INS1059

Page 1 of 1

Bonding Tips are used with the Bonding Station and Bonding System. The flat bottom machined surface of each Bonding Tip is used to apply heat and pressure to bond adhesive backed Circuit Frames to a circuit board surface. Bonding Tips are machined from high grade aluminum.

Circuit Frames are available in hundreds of shapes including lands, pads and edge contacts. See www.circuitmedic.com/products/circuitframes.html.



Pressure

Pressure is the recommended force in pounds to apply to the top surface of the replacement pad, land or conductor based on the Bonding Tip surface area. The recommended Bonding Pressure for Circuit Frames is 200 - 400 psi.

Setting

Setting corresponds to the indication on the scale of No. 115-4100 Bonding System. See www.circuitmedic.com/products/115-4100.html.

Available Bonding Tip Sizes

Part No.	Description	Pressure	Setting
115-2104	Bonding Tip, Tapered	N/A	N/A
115-2204	Bonding Tip, .080" (2.03 mm) Diameter	1.00 lbs	4
115-2206	Bonding Tip, .120" (3.05 mm) Diameter	2.26 lbs	9
115-2306	Bonding Tip, .040" x .060" (1.02 mm x 1.52 mm)	0.48 lbs	2
115-2316	Bonding Tip, .080" x .120" (2.03 mm x 3.05 mm)	1.92 lbs	8